

COVER FILM

ABSTRACT

Disclosed is a cover film and an electronic component package that uses the cover film as a lid material for a thermoplastic resin carrier tape, the cover film having at least a substrate layer (A), an intermediate layer (B), and a heat sealing layer (C) having a thermoplastic resin which can be heat-sealed to a carrier tape, the intermediate layer (B) including a metallocene straight-chain low density polyethylene, the metallocene straight-chain low density polyethylene having a TMA softening temperature of 90 to 109 °C according to JIS K7196, and the cover film in some instances having a release layer (D) between the intermediate layer (B) and the heat sealing layer (C).

Figure 1